

AMENDMENTSIn The Claims

1. (currently amended) A DCA memory module, comprising:
  - a substrate of a memory module;
  - at least a chip set of a single piece cut from a wafer, the chip set having a plurality of chips formed side by side with each other, wherein the chips are adhered on the substrate and are electrically connected to the substrate, a plurality of circuits not within the substrate are located within the chip set between the chips and electrically connect the chips to each other;  
and
  - a molding compound, encapsulating a portion of the electrical connection between the chip set and the substrate.
2. (original) The DCA memory module of claim 1, wherein the substrate comprises;
  - a plurality of patterned-trace layers; and
  - at least an insulating layer located in between the patterned-trace layers, wherein a plurality of vias are formed in the insulating layer and electrically connect the patterned-trace layers to each other.
3. (original) The DCA memory module of claim 2, wherein the insulating layer is made of a material selected from a group consisting of glass epoxy resin (FR-4, FR-5), bismaleimide-triazine (BT), epoxy resin or polyimide.
4. (original) The DCA memory module of claim 2, wherein the line-patterned layers are formed by defining copper foil using photolithography.
5. (original) The DCA memory module of claim 1, wherein the chip set is electrically connected

to the substrate by a flip-chip technology, and the molding compound fills into a gap located between the chip set and the substrate.

6. (original) The DCA memory module of claim 1, wherein the chip set is electrically connected to the substrate by a plurality of conductive wires, and the molding compound encapsulates the chip set and the conductive wires.
7. (original) The DCA memory module of claim 1, wherein the chip set comprises an even number of chips formed side by side as one group.
8. (original) The DCA memory module of claim 1, wherein the chip set comprises an even number chips and a total number of chips in the DCA memory module is eight.
9. (original) The DCA memory module of claim 1, wherein the chip set comprises an even number chips and a total number of chips in the DCA memory module is sixteen.
10. (original) The DCA memory module of claim 8, wherein the chip set comprises one of the number of the chips selecting from a group of two, four or eight chips.
11. (original) The DCA memory module of claim 9, wherein the chip set comprises one of the number of the chips selecting from a group of two, four or eight chips.
12. (currently amended) A DCA memory module, comprising:
  - a substrate of a memory module;
  - at least a chip set of a single piece cut from a wafer, for adhering onto the substrate and electrically connecting to the substrate, wherein the chip set has a plurality of chips formed side by side as one group, wherein the chip set further includes a circuit to couple the chips together; and
  - a molding compound, for encapsulating a portion of the electrical connection between the chip set and the substrate.

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13. (original) The DCA memory module of claim 12, wherein the chip set is electrically connected to the substrate by a flip-chip technology, and the molding compound fills into a gap located between the chip set and the substrate.
14. (original) The DCA memory module of claim 12, wherein the chip set is electrically connected to substrate by a plurality of conductive wires, and the molding compound encapsulates the chip set and the conductive wires.
15. (original) The DCA memory module of claim 12, wherein the chip set comprises eight chips formed side by side as one group.
16. (original) The DCA memory module of claim 12, wherein the chip set comprises an even number chips and a total number of chips in the chip set is eight.
17. (original) The DCA memory module of claim 12, wherein the chip set comprises an even number of chips and a total number of chips in the chip set is sixteen.
18. (original) The DCA memory module of claim 16, wherein the chip set comprises one of the number of the chips selecting from a group of two, four or eight chips.
19. (original) The DCA memory module of claim 17, wherein the chip set comprises one of the number of the chips selecting from a group of two, four or eight chips.
- 20-28. (cancelled)